

## SMD0805 Series

### Features

- Surface Mount Devices
- Lead free device
- Size 2.0\*1.2 mm / 0.08\*0.05 inch
- Surface Mount packaging for automated assembly

### Applications

- Almost anywhere there is a low voltage power supply, up to 15V and a load to be protected, including:
- Computer mother board, Modem, USB hub
  - PDAs & Charger, Analog & digital line card
  - Digital cameras, Disk drivers, CD-ROMs,

Alpha-Top (Sea & Land Alliance)

### Performance Specification

Model	Marking	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Typ. (W)	Maximum Time To Trip		Resistance		Agency Approval	
							Current (A)	Time (Sec)	R <sub>i min</sub> (Ω)	R <sub>1 max</sub> (Ω)	UL	TUV
SMD0805-010	1	15.0	100	0.10	0.30	0.5	0.5	1.50	1.000	6.000		
SMD0805-020	2	9.0	100	0.20	0.50	0.5	8.0	0.02	0.650	3.500	✓	
SMD0805-035	3	6.0	100	0.35	0.75	0.5	8.0	0.10	0.250	1.200	✓	
SMD0805-050	5	6.0	100	0.50	1.00	0.5	8.0	0.10	0.150	0.850	✓	
SMD0805-075	7	6.0	40	0.75	1.50	0.6	8.0	0.20	0.090	0.385	✓	
SMD0805-100	0	6.0	100	1.00	1.95	0.6	8.0	0.30	0.060	0.230	✓	✓
SMD0805-110	0	6.0	100	1.10	2.20	0.6	8.0	0.30	0.060	0.210	✓	
SMD0805-125	12	6.0	100	1.25	2.50	1.5	8.0	0.60	0.030	0.140		

**I<sub>hold</sub>** = Hold Current. Maximum current device will not trip in 25°C still air.

**I<sub>trip</sub>** = Trip Current. Minimum current at which the device will always trip in 25°C still air.

**V<sub>max</sub>** = Maximum operating voltage device can withstand without damage at rated current (I<sub>max</sub>).

**I<sub>max</sub>** = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).

**P<sub>d</sub>** = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

**R<sub>imin/max</sub>** = Minimum/Maximum device resistance prior to tripping at 25°C.

**R<sub>1max</sub>** = Maximum device resistance is measured one hour post reflow.

**CAUTION** : Operation beyond the specified ratings may result in damage and possible arcing and flame.

### Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H., 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-202, Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

### Agency Approvals :



E201504(Alpha-Top)/E319079(Sea&Land)



NO. R-50141892

### Regulation/Standard:



2002/95/EC



EN14582

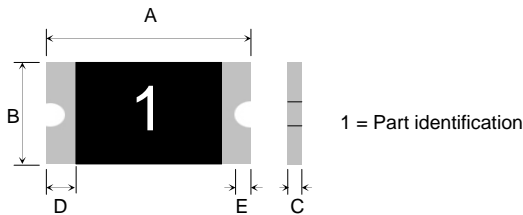
### I<sub>hold</sub> Versus Temperature

Model	Maximum ambient operating temperature (T <sub>mao</sub> ) vs. hold current (I <sub>hold</sub> )								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
SMD0805-010	0.14	0.12	0.11	0.10	0.08	0.07	0.06	0.05	0.03
SMD0805-020	0.28	0.25	0.23	0.20	0.17	0.14	0.12	0.10	0.07
SMD0805-035	0.47	0.44	0.39	0.35	0.30	0.27	0.24	0.20	0.14
SMD0805-050	0.68	0.62	0.55	0.50	0.40	0.37	0.33	0.29	0.23
SMD0805-075	1.00	0.90	0.79	0.75	0.63	0.57	0.53	0.41	0.34
SMD0805-100	1.35	1.25	1.15	1.00	0.82	0.74	0.65	0.55	0.42
SMD0805-110	1.45	1.35	1.20	1.10	0.92	0.84	0.75	0.65	0.52
SMD0805-125	1.65	1.53	1.36	1.25	1.05	0.95	0.85	0.74	0.59

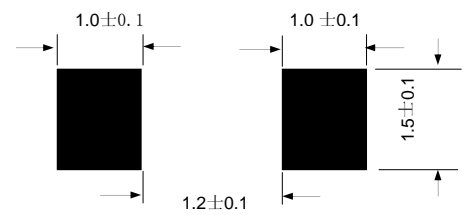
**Construction And Dimension (Unit:mm)**

Model	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.
SMD0805-010	2.00	2.20	1.20	1.50	0.50	1.00	0.20	0.20	0.10
SMD0805-020	2.00	2.20	1.20	1.50	0.50	1.00	0.20	0.20	0.10
SMD0805-035	2.00	2.20	1.20	1.50	0.50	1.00	0.20	0.20	0.10
SMD0805-050	2.00	2.20	1.20	1.50	0.30	0.60	0.20	0.20	0.10
SMD0805-075	2.00	2.20	1.20	1.50	0.50	1.10	0.20	0.20	0.10
SMD0805-100	2.00	2.20	1.20	1.50	0.50	1.10	0.20	0.20	0.10
SMD0805-110	2.00	2.20	1.20	1.50	0.50	1.10	0.20	0.20	0.10
SMD0805-125	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.20	0.10

**Dimensions & Marking**



**Recommended Pad Layout (mm)**



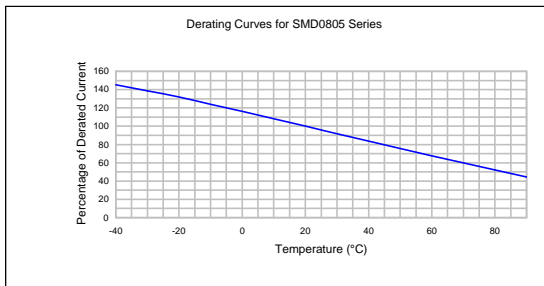
**Termination Pad Characteristics**

Terminal pad materials : Tin-plated Nickel-Copper  
 Terminal pad solderability : Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

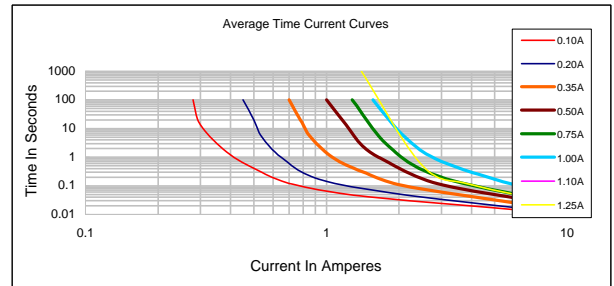
**Rework**

Use standard industry practices, the removal device must be replaced with a fresh one.

**Thermal Derating Curve**



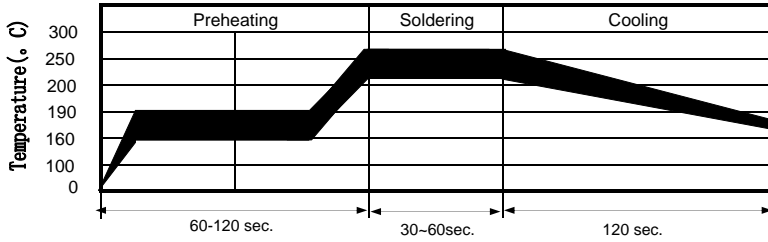
**Typical Time-To-Trip At 25°C**



**! WARNING:**

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability performance of our devices.

**Recommended Solder Reflow Conditions**

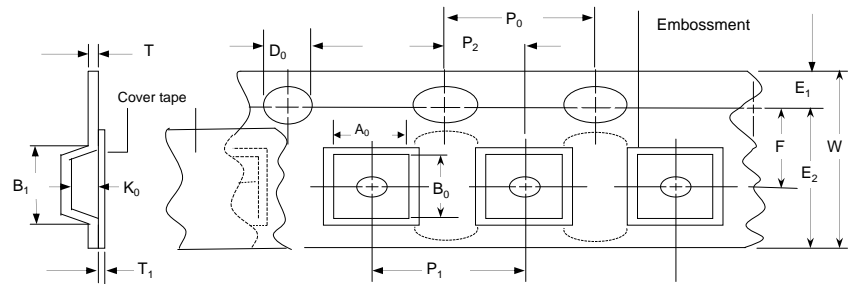


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

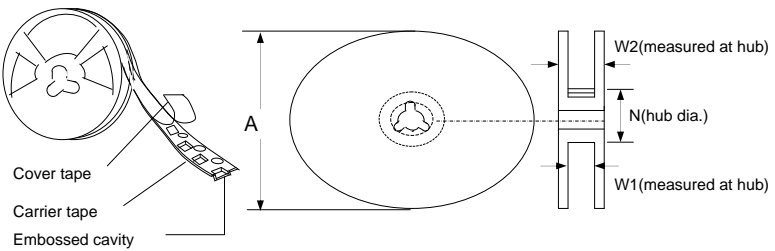
**Tape And Reel Specifications (mm)**

Governing Specifications	EIA 481-1
W	8.0 ± 0.3
P0	4.0 ± 0.10
P1	4.0 ± 0.10
P2	2.0 ± 0.05
A0	1.45 ± 0.10
B0	2.30 ± 0.10
B1max.	4.35
D0	1.55 + 0.1, -0
F	3.5 ± 0.05
E1	1.75 ± 0.10
E2min.	6.25
T	0.25
T1max.	0.1
K0	0.74 ± 0.1
Leader min.	390
Trailer min.	160
<b>Reel Dimensions</b>	
A max.	178
N min.	60
W1	9.0 ± 0.5
W2	12.0 ± 0.05

**EIA Tape Component Dimensions**



**EIA Reel Dimensions**



**Storage And Handling**

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

**Order Information**

SMD0805	010	Packaging	Tape & Reel Quantity
Product name	Hold		075,100,110,125
Size 2012 mm / 0805 inch	Current		The others
SMD: surface mount device	0.10A		4,000 pcs/reel
			5,000 pcs/reel

Tape & reel packaging per EIA481-1  
Labeling Information

**Sea & Land Electronic Corp.**

Model:      HF      Pb      RoHS

Part no.:

Spec.:

Lot no.:

Q'ty:

倉儲: 密封! 溫度: 18~33°C/濕度: 30~60% A

单击下面可查看定价，库存，交付和生命周期等信息

[>>SEA-LAND\(台湾陆海\)](#)